Minutes from OpenPICs WP 3 meeting 19-06-2017

Part I (14:00-15:00): Weiming (chairing), Rui, Roel, Rob, Steven, Ronald, Kevin, Meint, Longfei, Saeed, Michael

Discussion/action points

Nr.	Description	Responsible
1.	**Planning WP3 design on MPW** Revision of chip allocation for WP3 on MPW runs	
2.	**Allocation for test structures** If space is available or urgent test of designs is important, 1 month before the tape-out, notice should be given to Smart to include said designs.	Ronald, Weiming
3.	**Mode mismatch issue Triplex-InP** Contact Lionix to work out solutions for the mode mismatch problem discussed between Smart MPW chips and Triplex chips.	Ronald
4	**Standardization of pad layout for both wafer and die tester** Assure the compatibility of test cells for wafer and die tester. Keep aligned with PixApp standards.	Rui, Weiming

Next meeting is 17th July, 2017, 14:00

Part II (14:00-15:00): Weiming (chairing), Ronald, Kevin, Xaveer, Meint

Discussion/action points

Nr.	Description	Responsible
1.	**Measurement Template** Draft measurement template for capturing meta data using mark-up language such as Jasen. This will be useful for both efficient storing and exchange of measurement data.	Weiming
2.	**Library management** JePPIX should have an overview of library components with information that it can offer during the MPW ordering procedure.	

Next meeting is 17th July, 2017, 15:00